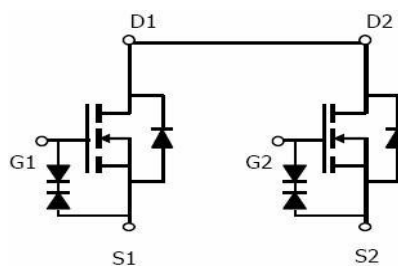




### Dual N-Channel Enhancement Mode Power MOSFET

#### Description

The MXN3384 uses advanced trench technology design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications. It is ESD protected

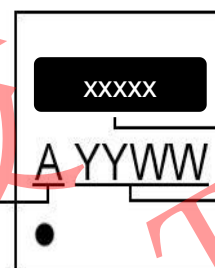


Schematic diagram

#### General Features

- ◆  $V_{DS} = 20V$ ,  $I_D = 6A$
- ◆ @ $V_{GS} = 4.5V$   $R_{DS(ON)}(Typ.) = 12.5m\Omega$
- ◆ @ $V_{GS} = 3.8V$   $R_{DS(ON)}(Typ.) = 13m\Omega$
- ◆ @ $V_{GS} = 2.5V$   $R_{DS(ON)}(Typ.) = 16.5m\Omega$

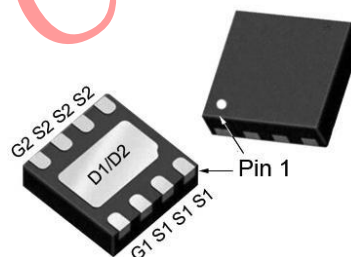
High density cell design for ultra low  $R_{dson}$   
Fully characterized Avalanche voltage and current



Marking Description

#### Application

- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply



DFN3x3-8L top view

#### Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous	$I_D$	6	A
Drain Current-Pulsed (Note 1)	$I_{DM}$	36	A
Maximum Power Dissipation	$P_D$	2.5	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ C$

#### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	50	$^\circ C/W$
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### Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	20	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V	-	-	1	μA
<b>Parameter</b>						
<b>Symbol</b>						
<b>Condition</b>						
<b>Min</b>						
<b>Typ</b>						
<b>Max</b>						
<b>Unit</b>						
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics (Note 2)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	0.45	0.65	1.2	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =6A	-	12.5	17	mΩ
		V <sub>GS</sub> =3.8V, I <sub>D</sub> =6A	-	13	19	
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =4A	-	16.5	24	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =10A	15	-	-	S
<b>Dynamic Characteristics (Note 3)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, F=1.0MHz	-	976	-	PF
Output Capacitance	C <sub>oss</sub>		-	80	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	142	-	PF
<b>Switching Characteristics (Note 3)</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =10V, I <sub>D</sub> =1A  V <sub>GS</sub> =10V, R <sub>GEN</sub> =6Ω  V <sub>DS</sub> =10V, I <sub>D</sub> =6A, V <sub>GS</sub> =4.5V	-	7.2	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	12	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	22.8	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	8.1	-	nS
Total Gate Charge	Q <sub>g</sub>		-	11	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	2.6	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	-	3	-	nC	
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 2)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A	-	-	1.2	V
Diode Forward Current (Note 1)	I <sub>S</sub>		-	-	3.5	A

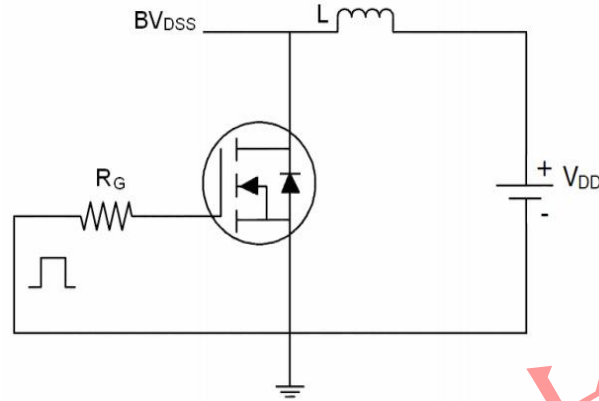
#### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

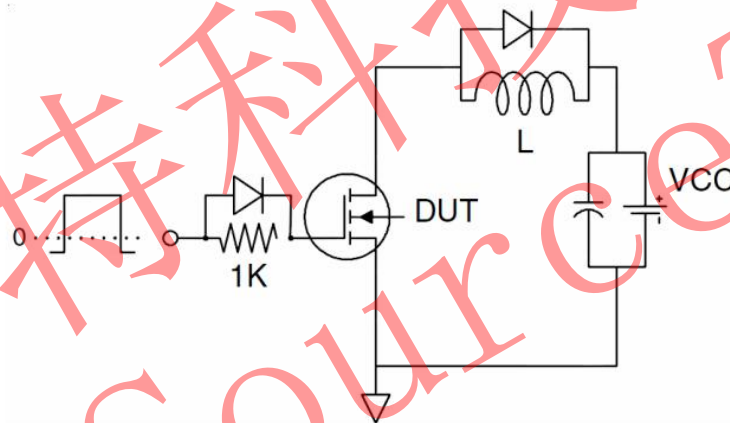


## Test Circuit

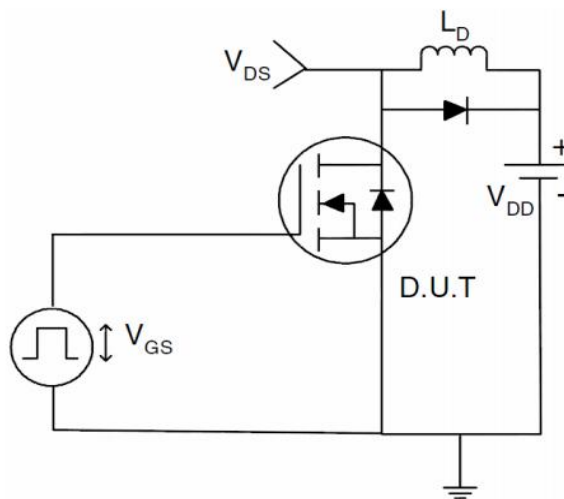
### 1) E<sub>AS</sub> Test Circuits



### 2) Gate Charge Test Circuit:



### 3) Switch Time Test Circuit:





Typical Electrical and Thermal Characteristics (Curves)

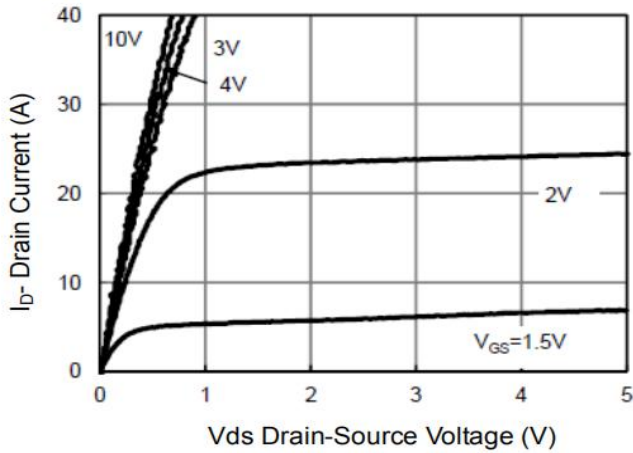


Figure 1 Output Characteristics

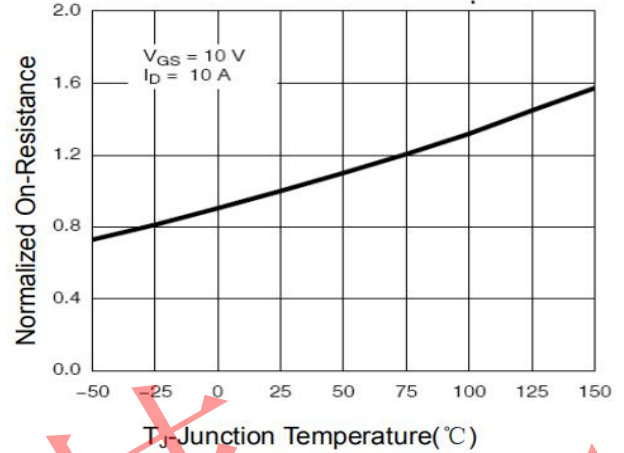


Figure 4 Rdson-Junction Temperature

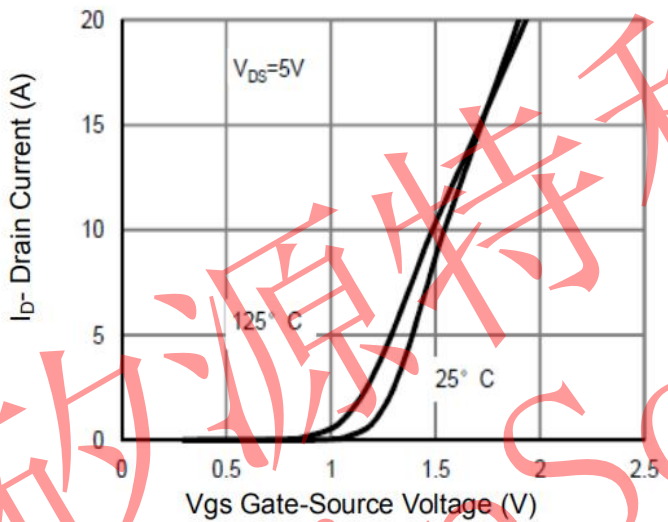


Figure 2 Transfer Characteristics

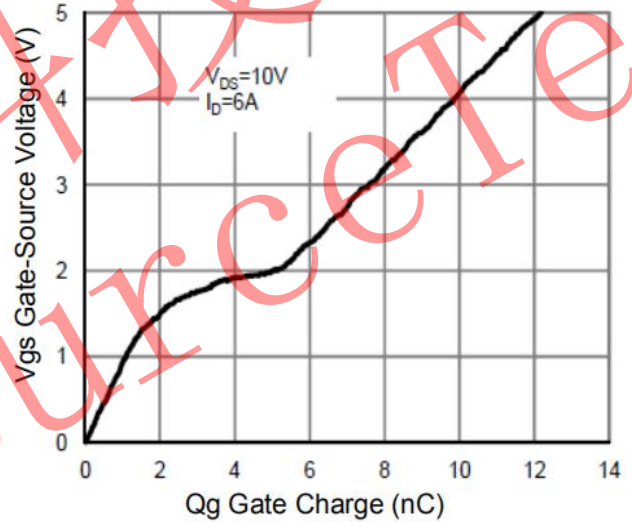


Figure 5 Gate Charge

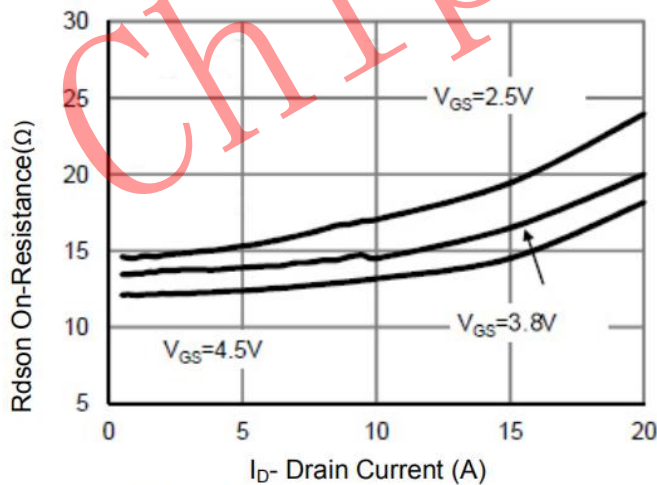


Figure 3 Rdson- Drain Current

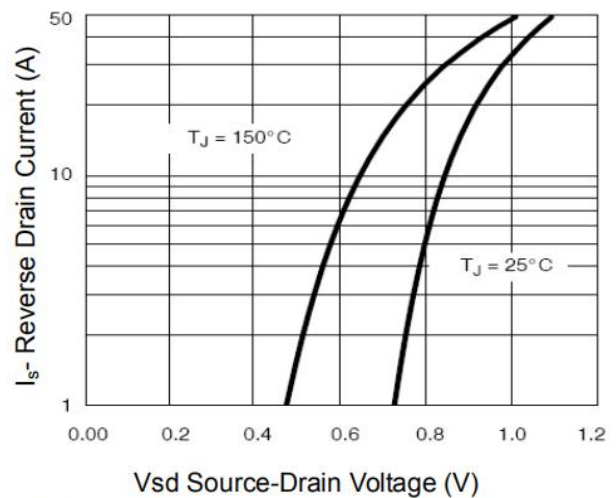


Figure 6 Source- Drain Diode Forward



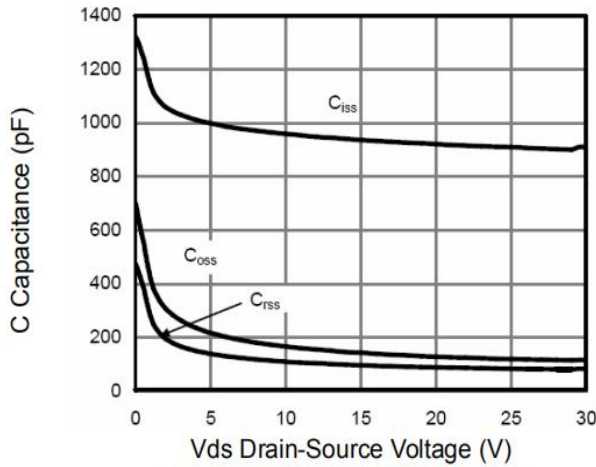


Figure 7 Capacitance vs Vds

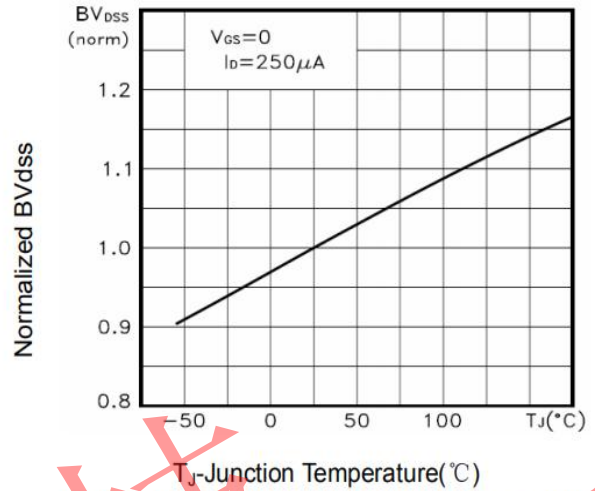


Figure 9  $BV_{DSS}$  vs Junction Temperature

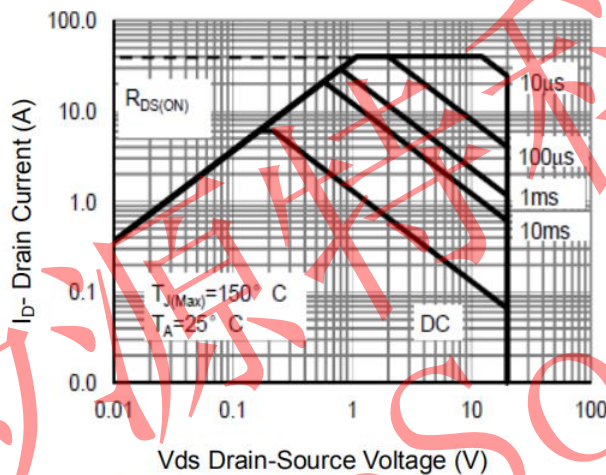


Figure 8 Safe Operation Area

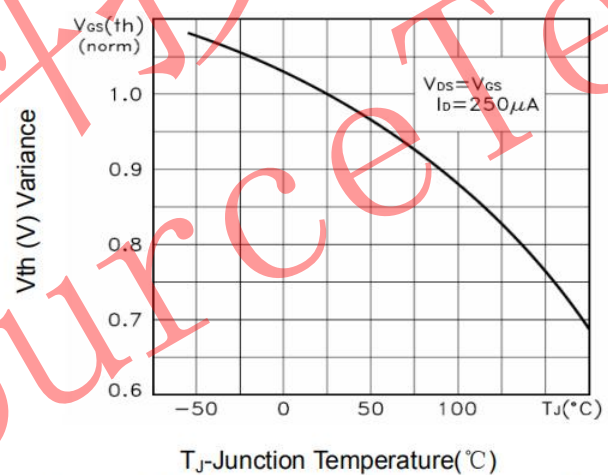


Figure 10  $V_{GS(th)}$  vs Junction Temperature

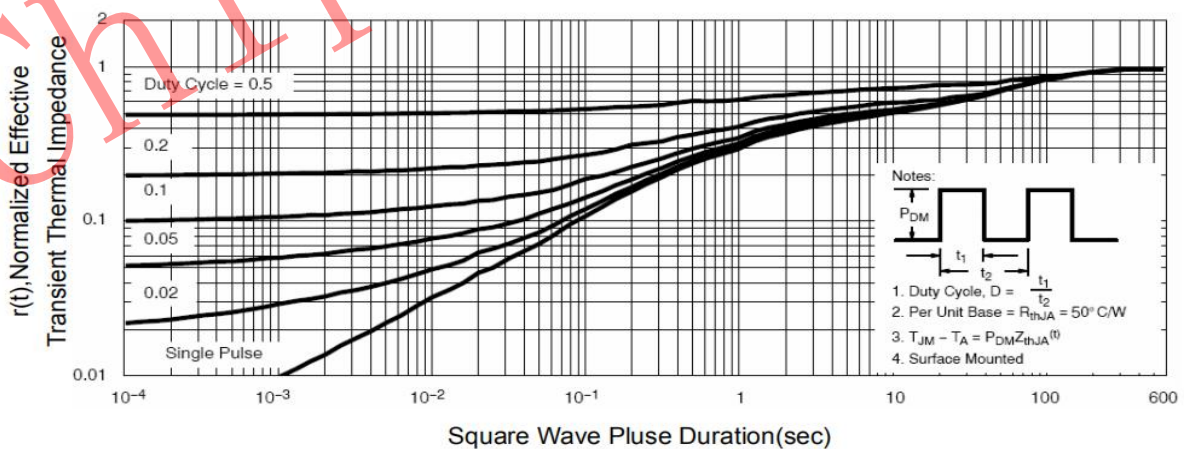


Figure 11 Normalized Maximum Transient Thermal Impedance



Package Dimension

DFN 3x3 MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	0.7		0.8	I		0.203	
B	0.25		0.35	J	2.2		2.4
C	0.2			K	1.4		1.6
D	2.924		3.076				
E	2.924		3.076				
F	0.324		0.476				
G		0.65					
H	0		0.05				

